

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/27/2022

Details for "SN74ABT574ADW"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74ABT574ADW	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DW 20	7.52x12.82x2.35	567.1

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.109524	99.998174	999982	0.019314	193
Precious Metals	Silver	7440-22-4	0.000002	0.001826	18	0	0
Sub-Total			0.109526	100	1000000	0.019315	193
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.414812	80	800000	0.073151	732
Thermoplastics	Epoxy	85954-11-6	0.103703	20	200000	0.018288	183
Sub-Total			0.518515	100	1000000	0.091439	914
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	131.268499	97.425	974250	23.14886	231489
Copper and Its Alloys	Iron	7439-89-6	3.233712	2.4	24000	0.570257	5703
Copper and Its Alloys	Phosphorus	7723-14-0	0.020211	0.015	150	0.003564	36
Copper and Its Alloys	Tin	7440-31-5	0.040421	0.03	300	0.007128	71
Copper and Its Alloys	Zinc	7440-66-6	0.134738	0.1	1000	0.023761	238
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.040421	0.03	300	0.007128	71
Sub-Total			134.738002	100	1000000	23.760698	237607
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.318406	92.559884	925599	0.05615	562
Precious Metals	Gold	7440-57-5	0.005642	1.640116	16401	0.000995	10
Precious Metals	Palladium	7440-05-3	0.019952	5.8	58000	0.003518	35
Sub-Total			0.344	100	1000000	0.060664	607
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	378.096749	88	880000	66.676384	666764
Other Plastics and Rubber	Carbon Black	1333-86-4	1.288966	0.3	3000	0.227306	2273
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.363105	0.55	5500	0.416727	4167
Thermoplastics	Epoxy	85954-11-6	47.906577	11.15	111500	8.448201	84482
Sub-Total			429.655397	100	1000000	75.768619	757686
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.697026	100	1000000	0.299266	2993
Sub-Total			1.697026	100	1000000	0.299266	2993
Total			567.062466			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 08/27/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.